

## **AMENDMENTS TO THE CLAIMS:**

### **Complete Listing of Claims**

Claims 1-12. (canceled)

Claim 13. (currently amended) A semiconductor device comprising a die and a substrate and formed by the process of:

- (a) applying an electrically non-conductive material covering at least a portion of said die and extending onto said substrate to a plurality of contact pads formed on said substrate to form a layer of the non-conductive material; and
- (b) applying an electrically conductive material over said non-conductive material layer and extending from an electrical point of contact of said die to at least one contact pad on said substrate, wherein the conductive material is separated into a plurality of conductive patches by laser trimming away portions of the conductive material.

Claim 14. (canceled).

Claim 15. (currently amended) ~~The~~ A device as claimed in claim 13, wherein a hole is trimmed into the non-conductive material layer over and down to at least one the bond pad pads, exposing at least a portion of each bond pad to be connected.

Claim 16. (currently amended) ~~The~~ A device as claimed in claim 13, wherein an electrically conductive bump is formed on each said die bond pad, said bump protruding through said non-conductive material layer and at least partially through said conductive material layer.

Claim 17. (currently amended) ~~The A device as claimed in claim 13, wherein the non-conductive material insulating layer~~ comprises a non-conductive epoxy.

Claim 18. (currently amended) ~~The A device as claimed in claim 13, wherein the non-conductive material insulating layer~~ comprises a non-conductive polyimide.

Claim 19. (currently amended) ~~The A device as claimed in claim 13, wherein the conductive material layer~~ comprises conductive ink.

Claim 20. (currently amended) ~~The A device as claimed in claim 13, wherein the conductive material layer~~ comprises a metal ion coating.

Claims 21-24. (canceled)